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FORM PTO-1595

(Rev. 8-93)

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U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party:
Ahmad HamzehdoostAdditional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

2. Name and address of receiving party(ies)

Name: VLSI Technology, Inc.

Internal Address: _____

Street Address: 1109 McKay DriveCity: San Jose State: CA ZIP: 95131Additional name(s) & address(es) attached? ☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other _____Execution Date: November 30, 1998

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: 11/18/98

A. Patent Application No.(s)

09/195,349

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Patrick T. KingInternal Address: Law Office of Patrick
T. KingStreet Address: 3361 Aptos Rancho RoadCity: Aptos State: CA ZIP: 950036. Total number of applications and patents involved: 17. Total fee (37 CFR 3.41).....\$ 40.00☒ Enclosed☐ Authorized to be charged to deposit account

8. Deposit account number:

11-0979

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Patrick T. KingName of Person Signing
Reg. No. 28,231

Signature

2

Date

Total number of pages including cover sheet, attachments, and document: 2Mail documents to be recorded with required cover sheet information to:
Commissioner of Patents & Trademarks, Box Assignments
Washington, D.C. 20231

(Form PTO-1595—Recordation Form Cover Sheet [16-5]—page 1 of 3)

/04/1999 TL0011 00000004 09195349

FC:581

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PATENT
REEL: 9806 FRAME: 0038

Assignment

Whereas, I, **AHMAD HAMZEHDOST**
have invented certain new and useful improvements as described and set forth in the below-identified patent application, and VLSI Technology, Inc. (hereinafter called VLSI), a California Corporation having its principal place of business at 1109 McKay Drive, San Jose, CA 95131 is desirous of acquiring the entire right, title and interest in the said invention and application and in any Letters Patent which may be granted on the same;

Now, therefor, for and in consideration of the sum of \$1.00, receipt of which is hereby acknowledged, I do hereby sell, assign and transfer unto VLSI, its successors and assigns, the entire right, title and interest, including the right of priority in, to and under an application for Letters Patent of the United States entitled:

BGA PACKAGE USING PCB AND TAPE IN A DIE-UP CONFIGURATION

 filed herewith and the inventions set forth and described therein, and any and all Letters Patent of the United States and of countries foreign thereto which may be granted thereon or therefor; or
 X Serial No.: 09/195,349 filed on November 18, 1998 and the inventions set forth and described therein, and any and all Letters Patent of the United States and of countries foreign thereto which may be granted thereon or therefor;

And for the above consideration, I agree promptly upon request of VLSI, its successors or assigns, to execute and deliver without further compensation any power of attorney, assignment, application, whether original, continuation, divisional or reissue, or other papers which may be necessary or desirable fully to secure to VLSI, its successors and assigns, the inventions described in said application and all patent rights therein, in the United States and in any country foreign thereto, and to cooperate and assist in the prosecution of interference proceedings involving said inventions and in the adjudication or reexamination of said Letters Patent provided the expenses which may be incurred by me in lending such cooperation and assistance are paid by VLSI.

In witness whereof, I hereunto set my hand and seal:

Inventor's
Signature:

Ahmad Hamzehdost
AHMAD HAMZEHDOST

Date:

Nov, 30, 98